



(43) International Publication Date
22 September 2011 (22.09.2011)

PCT

(10) International Publication Number
WO 2011/116106 A2

(51) International Patent Classification:

H01L 23/48 (2006.01) *H01L 23/14* (2006.01)
H01L 21/60 (2006.01)

(21) International Application Number:

PCT/US2011/028689

(22) International Filing Date:

16 March 2011 (16.03.2011)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

12/725,925 17 March 2010 (17.03.2010) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report (Rule 48.2(g))

(54) Title: SYSTEM-IN-PACKAGE USING EMBEDDED-DIE CORELESS SUBSTRATES, AND PROCESSES OF FORMING SAME

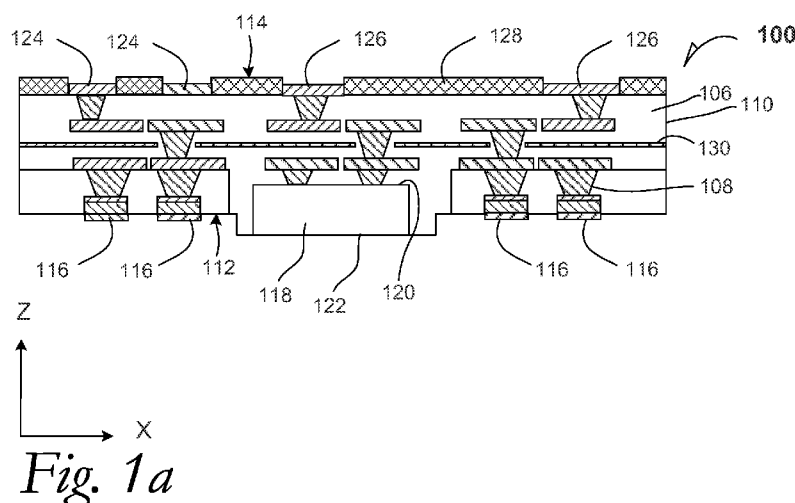


Fig. 1a

(57) Abstract: An apparatus includes a coreless substrate with an embedded die that is integral to the coreless substrate, and at least one device assembled on a surface that is opposite to a ball-grid array disposed on the coreless substrate. The apparatus may include an over-mold layer to protect the at least one device assembled on the surface.



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